Materials Declaration

Package	SC70
Body Size	--
LeadCount	4
Option	Pb-Free

Molding Compound

Item	% of Compound	Weight (g)	PPM
OCN	16	3.63 E-04	62874
SiO2	80	1.82 E-03	314368
Sb2O3	2.4	5.45 E-05	9431
Br	0.6	1.36 E-05	2358
Carbon Black	1	2.27 E-05	3930

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Fe	58.4	1.50 E-03	258807
Ni	41	1.05 E-03	181696
Mn	0.4	1.02 E-05	1773
Si	0.2	5.12 E-06	886

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	1.00 E-04	17311

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100	5.83 E-04	100981

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	3.33 E-05	5770

Chip

	% of Chip	Weight (g)	PPM
Si	100	2.10 E-04	36353

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Resin	25	5.00 E-06	866
Ag Filler	75	1.50 E-05	2597

Package Totals

Weight (g)	PPM
5.78 E-03	1000000

Molding Compound

Item	PPM	Method
Pb	<10.38	ICP AES
Cd	0.0039	ICP AES
Hg	Not Detected	ICP AES
Cr+6	Not Detected	DIN 53314

Die Attach Paste

Item	PPM	Method
Pb	<5	ICP AES
Cd	<5	ICP AES
Hg	<5	ICP AES
Cr+6	<5	ICP AES
PBB	Not Detected	
PBDE	Not Detected	

CRS-KS-E

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ADI Proprietary

05/24/05

Materials Declaration

Package	SC70-ISOLATED BACKSIDE
Body Size	--
LeadCount	4
Option	Pb-free, Halide-free

Molding Compound

Substance	% of Compound	Weight (g)	PPM
Silica	80.8	2.63 E-03	465533
Epoxy resin	9.0	2.93 E-04	51854
Phenol Resin	5.0	1.63 E-04	28808
Metal Hyroxide	5.0	1.63 E-04	28808
Carbon Black	0.2	6.52 E-06	1152
Subtotal	100.0	3.26 E-03	576154

Leadframe

Substance	% of Leadframe	Weight (g)	PPM
Iron	56.7	1.02 E-03	180556
Nickel	41.5	7.48 E-04	132153
Manganese	0.8	1.44 E-05	2548
Cobalt	0.5	9.01 E-06	1592
Silicon	0.3	5.41 E-06	955
Chromium	0.1	1.80 E-06	318
Aluminum	0.1	1.80 E-06	318
Subtotal	100	1.80 E-03	318440

Internal Leadframe Plating

Substance	% of Plating	Weight (g)	PPM
Silver	100	1.82 E-05	3217

External Leadframe Plating

Substance	% of Plating	Weight (g)	PPM
Tin	100	3.18 E-04	56238

Bond Wires

Substance	% of Wire	Weight (g)	PPM
Gold	99.99	3.00 E-05	5302

Chip

Substance	% of Chip	Weight (g)	PPM
Doped Silicon	100	2.10 E-04	37114

Die Attach

Substance	% of Die Attach	Weight (g)	PPM
Silicon Dioxide	46.00	9.20 E-06	1626
Epoxy Resin	46.00	9.20 E-06	1626
Curing agent & hardener	8.00	1.60 E-06	283
Subtotal	100	2.00 E-05	3535

Molding Compound

Substance	PPM	Method
Lead	Not Detected	Draft IEC 62321. ICP-OES.
Cadmium	Not Detected	Draft IEC 62321. ICP-OES.
Mercury	Not Detected	Draft IEC 62321. ICP-OES.
Chromium+6	Not Detected	Draft IEC 62321. UV-VIS.
Polybrominated biphenyls (PBB)	Not Detected	Draft IEC 62321. GC-MSD.
Polybrominated Diphenyl Ethers (PBDE)	Not Detected	Draft IEC 62321. GC-MSD.

Die Attach Paste

Substance	PPM	Method
Lead	Not Detected	Draft IEC 62321. ICP-OES.
Cadmium	Not Detected	Draft IEC 62321. ICP-OES.
Mercury	Not Detected	Draft IEC 62321. ICP-OES.
Chromium+6	Not Detected	Draft IEC 62321. UV-VIS.
Polybrominated biphenyls (PBB)	Not Detected	Draft IEC 62321. GC-MSD.
Polybrominated Diphenyl Ethers (PBDE)	Not Detected	Draft IEC 62321. GC-MSD.

Package Totals

Weight (g)	PPM
5.66 E-03	1000000

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Materials Declaration

Package	SC70 - COL
Body Size	--
LeadCount	4
Option	NiPdAu

Molding Compound

Substance	% of Compound	Weight (g)	PPM
Silica	87.3	2.85 E-03	489006
Phenol Resin	4.5	1.47 E-04	25207
Epoxy Resin 1	3.0	9.78 E-05	16804
Epoxy Resin 2	3.0	9.78 E-05	16804
Others	2.0	6.52 E-05	11203
Carbon Black	0.2	6.52 E-06	1120
Subtotal	100	3.26 E-03	560145

Leadframe

Substance	% of Leadframe	Weight (g)	PPM
Copper	97.5	2.21 E-03	380428
Iron	2.35	5.34 E-05	9169
Zinc	0.12	2.72 E-06	468
Phosphorus	0.03	6.81 E-07	117
Subtotal	100	2.27 E-03	390182

Internal Leadframe Plating/External Leadframe Plating

Substance	% of Plating	Weight (g)	PPM
Nickel	90.91	2.65 E-05	4545
Palladium	7.91	2.30 E-06	395
Gold	1.19	3.45 E-07	59
Subtotal	100.00	2.91 E-05	4999

Bond Wires

Substance	% of Wire	Weight (g)	PPM
Gold	99.99	3.00 E-05	5154

Chip

Substance	% of Chip	Weight (g)	PPM
Doped Silicon	100	2.10 E-04	36083

Die Attach

Substance	% of Die Attach	Weight (g)	PPM
Epoxy Resin	31	6.20 E-06	1065
Metal Oxide	31	6.20 E-06	1065
Glycol ethers	22	4.40 E-06	756
Silica	8	1.60 E-06	275
Curing agent & hardener	8	1.60 E-06	275
Subtotal	100	2.00 E-05	3436

Molding Compound

Substance	PPM	Method
Lead	Not Detected	USEPA 3050B. ICP-OES.
Cadmium	Not Detected	EN1122, method B:2001. ICP-OES.
Mercury	Not Detected	USEPA 3052. ICP-OES.
Chromium+6	Not Detected	EPA 3060A/7196A. UV-VIS.
Polybrominated biphenyls (PBB)	Not Detected	EPA 3540C/3550B. GC-MS.
Polybrominated Diphenyl Ethers (PBDE)	Not Detected	EPA 3540C/3550B. GC-MS.

Die Attach

Substance	PPM	Method
Lead	Not Detected	Draft IEC 62321. ICP-OES.
Cadmium	Not Detected	Draft IEC 62321. ICP-OES.
Mercury	Not Detected	Draft IEC 62321. ICP-OES.
Chromium+6	Not Detected	Draft IEC 62321. UV-VIS.
Polybrominated biphenyls (PBB)	Not Detected	Draft IEC 62321. GC-MSD.
Polybrominated Diphenyl Ethers (PBDE)	Not Detected	Draft IEC 62321. GC-MSD.

Package Totals

Weight (g)	PPM
5.82 E-03	1000000

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ADI Proprietary

Materials Declaration

Package	SC70
Body Size	--
LeadCount	4
Option	Sn/Pb

Molding Compound

Item	% of Compound	Weight (g)	PPM
OCN	16	3.63 E-04	62874
SiO2	80	1.82 E-03	314368
Sb2O3	2.4	5.45 E-05	9431
Br	0.6	1.36 E-05	2358
Carbon Black	1	2.27 E-05	3930

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Fe	58.4	1.50 E-03	258807
Ni	41	1.05 E-03	181696
Mn	0.4	1.02 E-05	1773
Si	0.2	5.12 E-06	886

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	1.00 E-04	17311

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	85	4.96 E-04	85834
Pb	15	8.75 E-05	15147

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	3.33 E-05	5770

Chip

	% of Chip	Weight (g)	PPM
Si	100	2.10 E-04	36353

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Resin	25	5.00 E-06	866
Ag Filler	75	1.50 E-05	2597

Package Totals

Weight (g)	PPM
5.78 E-03	1000000

Molding Compound

Item	PPM	Method
Pb	<10.38	ICP AES
Cd	0.0039	ICP AES
Hg	Not Detected	ICP AES
Cr+6	Not Detected	DIN 53314

Die Attach Paste

Item	PPM	Method
Pb	<5	ICP AES
Cd	<5	ICP AES
Hg	<5	ICP AES
Cr+6	<5	ICP AES
PBB	Not Detected	
PBDE	Not Detected	

CRS-KS-A

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